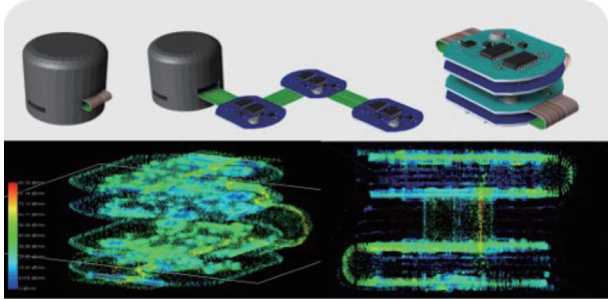


Cadence RF & System Analysis Solutions

■ Cadence Clarity for 3D Structure Model Extraction & EM Analysis

Cadence Clarity는 PCB, IC Package, System on IC(SoIC) 설계에 있어서 주요한 상호연결구조에 대한 True 3D Tool로서 복잡한 3D 구조물에 대해 3D Electromagnetic(EM) Solve와 혁신적인 멀티프로세싱 분산처리 기술을 통해 거대 연산구조에 대해서도 빠르고 정확한 Model Extraction 환경 및 2D, 3D EM해석결과를 통해 EMC 분석환경을 제공합니다.

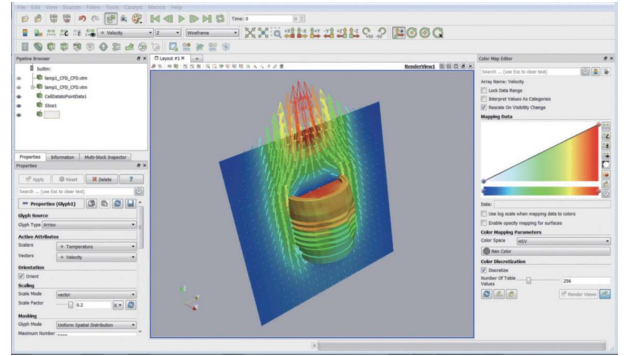
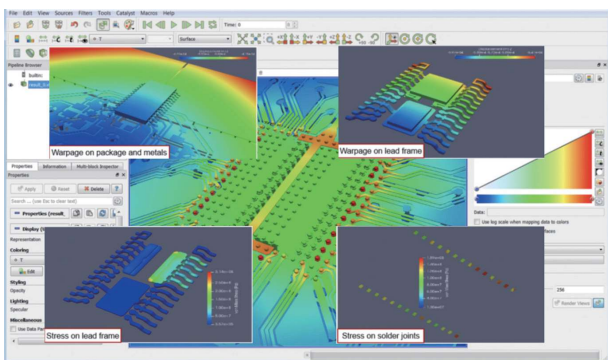


Features

- Enhanced usability: Automatically matches computing resources available to the structure being solved, so 3D experts and non-3D experts can get accurate results in a timely manner
- Breakthrough parallelization: Allows engineering managers more flexibility when budgeting for computer configurations required for 3D simulation
- Flexibility: Brings true 3D analysis to any engineer with either desktop, on- premises, or cloud HPC resources
- Maximizing resources: No fear of early termination due to computer resources being fully consumed if only a small number of cores is available
- Available to users of all design platforms: Easily reads design data from all standard chip, IC package, and PCB platforms
- Integrated 3D solutions: Easily integrate with Cadence Allegro® Package Designer Plus SiP Layout Option, Virtuoso®, and Allegro platforms to optimize in the analysis tool and implement in the design tool without being redrawn
- Model EM interface: Merge mechanical structures such as cables and connectors with their system design and model an EM interface as a single model

■ Cadence Celsius for 3D Structure Thermal Analysis

Cadence Celsius Thermal Solver는 IC Package, PCB 및 System에 대해 과도상태 및 정상상태의 Thermal 분석을 쉽고 빠르게 해석할 수 있도록 지원합니다.

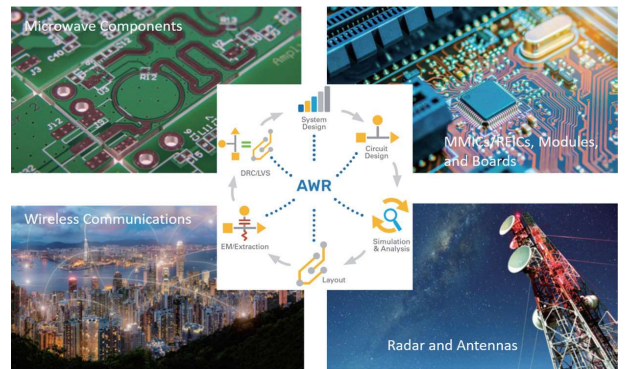


Features

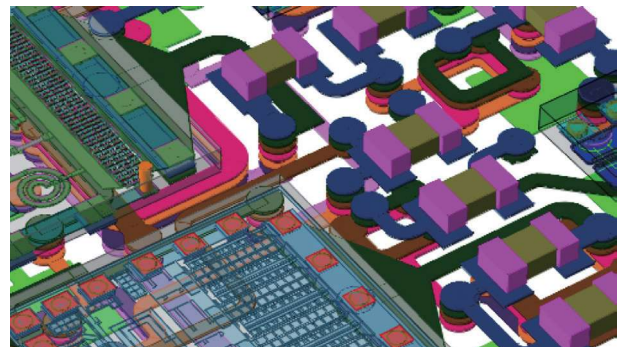
- Massive Parallel Computational Solvers : 2.5D & 3D FEA Field Solver, CFD Solver
- Sigrity 3D Workbench for modeling and thermal analysis environment
- Thermal Stress and Strain : Accurately simulates thermal-induced stress and strain in solids
- Provide conclusive thermal analysis capabilities for chip, package, PCB, and electronic systems

■ Cadence AWR for RF / Microwave Solutions

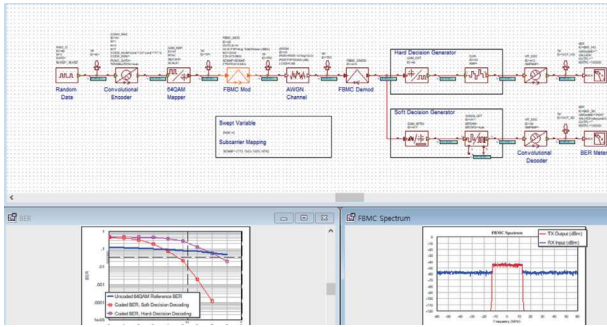
Cadence AWR for RF / Microwave Solution은 RF에서부터 Millimeter-wave(mmWave)까지 모바일 디바이스, 통신인프라, 우주항공 및 방산 분야에 적용되는 RFIC, MMIC부품, PCB, Multi-technology module 및 Wireless System 설계 및 검증에 필요한 환경을 제공합니다.



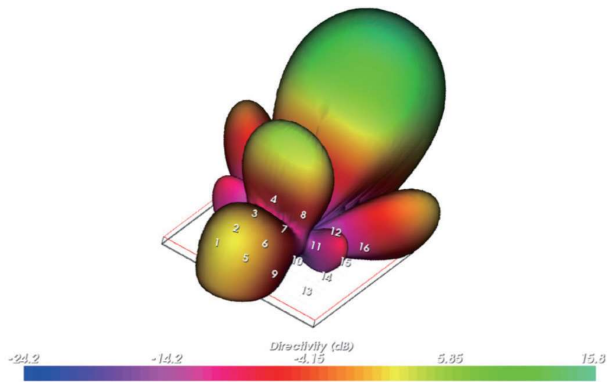
AWR Microwave Office - RF and Microwave Circuit Design Software for MMIC, PCB and Module



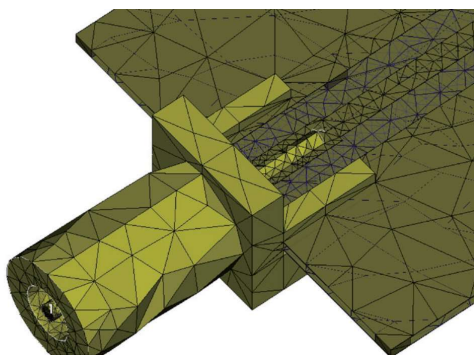
AWR Visual System Simulator - Communications/Radar systems design software



AWR AXIEM for 3D Planar EM Solver helps engineers design, optimize, and integrate antennas/arrays, providing powerful EM technologies to simulate antenna metrics such as gain, return loss, radiation efficiency, and currents, and to visualize 2D/3D far-field antenna patterns.

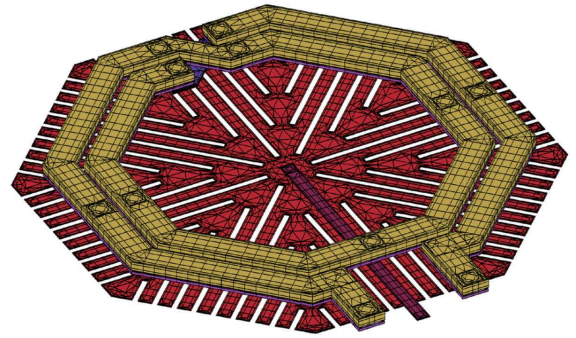


AWR Analyst Full 3D FEM EM Solver accelerates high-frequency product development from early physical design characterization through to full 3D EM verification. The 3D FEM solver provides fast and accurate EM analysis so engineers can achieve higher performance in less development time for greater first-pass success.

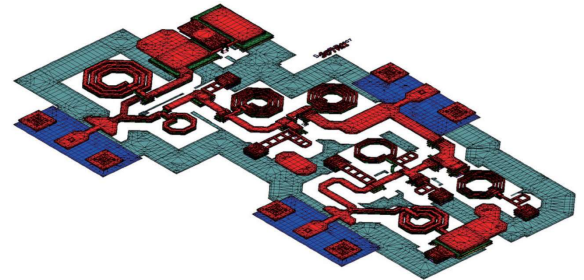


■ Cadence EMX Planar 3D Solver

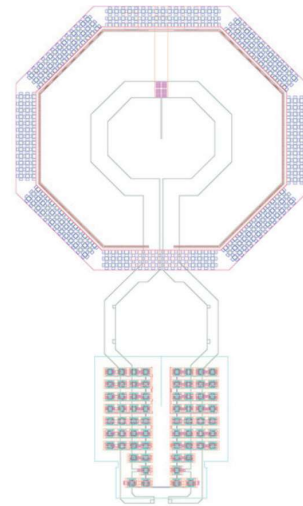
Cadence EMX Planar 3D Solver는 고주파, RF 및 Mixed-Signal IC에 대한 Electromagnetics Simulator로서 대형 RF 회로블록에 대해 효율적이고 정밀한 설계가 가능하며 수동소자의 동작특성분석 및 Interconnect에 의한 기생성분을 분석할 수 있습니다.



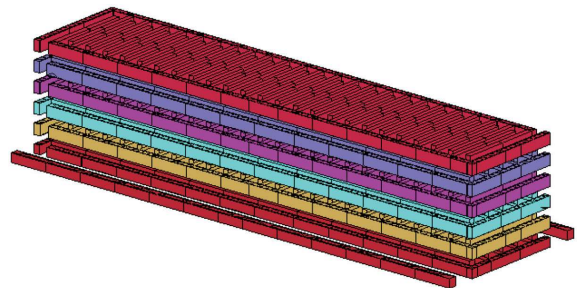
< Inductor with Shield >



< Full RF Circuit >



< VCO >



< MoM Capacitor >

Applications

- Passive component libraries
- Design of spiral inductors, MOM capacitors, MIM capacitors, baluns and transformers.
- RFIC circuits, VCOs, LNAs
- Design of RF test structures
- High-Q passive-in-package filters
- Design high power distributed RF amplifiers